

WAFER MANUFACTURING METHOD

ABSTRACT

A wafer manufacturing method includes a Z-coordinate measurement step of deeming a separation layer to be formed as an XY plane and measuring a height $Z_{(x, y)}$ of an upper surface of an ingot to be irradiated with a laser beam, corresponding to the X-coordinate and the Y-coordinate, and a calculation step of defining a Z-coordinate of the separation layer to be formed as Z_0 and calculating a difference from the measured height $Z_{(x, y)}$ ($Z_{(x, y)} - Z_0$) to obtain a Z-coordinate of a beam condenser. The wafer manufacturing method includes also a separation layer forming step of relatively moving a holding unit and the beam condenser in an X-axis direction and a Y-axis direction, moving the beam condenser in a Z-axis direction on the basis of the Z-coordinate obtained in the calculation step to position a focal point to Z_0 .

[Fig. 4]